

Intel Platform Memory Operations

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DDR4 LRDIMM System-Level Validation Results on Intel® Xeon® E7-8800/4800 v3 Processor Family

Listed below are the results from a small sample of DDR4 LRDIMMs tested on Intel® Xeon® E7-8800/4800 v3 processor family. We are providing this information as a guide to module compatibility with Intel server reference platforms. This testing is not intended to replace the normal OEM qualification process. For results on specific Intel® motherboards or OEM production motherboards, please refer to the OEM's list of qualified memory suppliers.

February 8th, 2016

LRDIMM QR DDR4- 1:1 Mode												
1866 1.2V 1DIMM and 2DIMMs per channel; 2 slots per channel; 4 channels												
1866 1.2V 1DIMM and 2DIMMs per channel; 3 slots per channel; 4 channels												
1600 1.2V 3DIMMs per channel; 3 slots per channel; 4 channels												
DIMM					DRAM					Buffer		
Supplier	Part Number	Size	CL	Raw Card	Supplier	Part Number	Density Die	Width	Date Code	Vendor	Revision	Note
Samsung	M386A4G40DM0-CPB	32GB	15	D	Samsung	K4A8G045WD-MCPB	4Gb	x4	1434	IDT	C0 / B1	
Samsung	M386A4G40DM0-CPB	32GB	15	D	Samsung	K4A8G045WD-MCPB	4Gb	x4	1434	Montage	B1 / A1	
Samsung	M386A8K40BM1-CPB	64GB	15	D	Samsung	K4AAG045WB-BCPB	8Gb	x4	1516	IDT	C0 / B1	
Samsung	M386A8K40BM1-CPB	64GB	15	D	Samsung	K4AAG045WB-BCPB	8Gb	x4	1520	Montage	C0 / B0	
SK hynix	HMA84GL7MMR4N-TFTD	32GB	15	D	SK hynix	H5AN8G4NMMR-TFC	4Gb	x4	1434	IDT	C0 / B1	
SK hynix	HMA84GL7MMR4N-TFT1	32GB	15	D	SK hynix	H5AN8G4NMMR-TFC	4Gb	x4	1446	Montage	B1 / A1	
SK hynix	HMAA8GL7MMR4N-TFTD	64GB	15	E	SK hynix	H5ANAG4NMMR-TFC	8Gb	x4	1514	IDT	C0 / B1	
SK hynix	HMAA8GL7MMR4N-TFT1	64GB	15	E	SK hynix	H5ANAG4NMMR-TFC	8Gb	x4	1514	Montage	B1 / A1	
SK hynix	HMA84GL7AMR4N-TFT2	32GB	15	D1	SK hynix	H5AN8G4NAMR-TFC	4Gb	x4	1527	Montage	C0/B0	
SK hynix	HMA84GL7AMR4N-TFTE	32GB	15	D1	SK hynix	H5AN8G4NAMR-TFC	4Gb	x4	1525	IDT	C0/A3	
Micron	MTA72ASS4G72LZ-2G1A1	32GB	15	E	Micron	MT40A2G4TRF-093E:A	4Gb	x4	1418	IDT	C0 / B1	
Micron	MTA72ASS4G72LZ-2G1A1	32GB	15	E	Micron	MT40A2G4TRF-093E:A	4Gb	x4	1418	Montage	B1 / A1	

LRDIMM QR DDR4- 2:1 Mode												
1600 1.2V 1DIMM and 2DIMMs per channel; 2 slots per channel; 4 channels												
1600 1.2V 1DIMM, 2DIMMs and 3DIMMs per channel; 3 slots per channel; 4 channels												
DIMM					DRAM					Buffer		
Supplier	Part Number	Size	CL	Raw	Supplier	Part Number	Density	Width	Date	Vendor	Revision	Note
Samsung	M386A4G40DM0-CPB	32GB	15	D	Samsung	K4A8G045WD-MCPB	4Gb	x4	1434	IDT	C0 / B1	
Samsung	M386A4G40DM0-CPB	32GB	15	D	Samsung	K4A8G045WD-MCPB	4Gb	x4	1434	Montage	B1 / A1	
Samsung	M386A8K40BM1-CPB	64GB	15	D	Samsung	K4AAG045WB-BCPB	8Gb	x4	1516	IDT	C0 / B1	
Samsung	M386A8K40BM1-CPB	64GB	15	D	Samsung	K4AAG045WB-BCPB	8Gb	x4	1520	Montage	C0 / B0	
SK hynix	HMA84GL7MMR4N-TFTD	32GB	15	D	SK hynix	H5AN8G4NMMR-TFC	4Gb	x4	1434	IDT	C0 / B1	
SK hynix	HMA84GL7MMR4N-TFT1	32GB	15	D	SK hynix	H5AN8G4NMMR-TFC	4Gb	x4	1446	Montage	B1 / A1	
SK hynix	HMAA8GL7MMR4N-TFTD	64GB	15	E	SK hynix	H5ANAG4NMMR-TFC	8Gb	x4	1514	IDT	C0 / B1	
SK hynix	HMAA8GL7MMR4N-TFT1	64GB	15	E	SK hynix	H5ANAG4NMMR-TFC	8Gb	x4	1514	Montage	B1 / A1	
SK hynix	HMA84GL7AMR4N-TFT2	32GB	15	D1	SK hynix	H5AN8G4NAMR-TFC	4Gb	x4	1527	Montage	C0/B0	

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LRDIMM QR DDR4- 2:1 Mode

1600 1.2V 1DIMM and 2DIMMs per channel; 2 slots per channel; 4 channels

1600 1.2V 1DIMM, 2DIMMs and 3DIMMs per channel; 3 slots per channel; 4 channels

DIMM					DRAM					Buffer		
Supplier	Part Number	Size	CL	Raw	Supplier	Part Number	Density	Width	Date	Vendor	Revision	Note
SK hynix	HMA84GL7AMR4N-TFTE	32GB	15	D1	SK hynix	H5AN8G4NAMR-TFC	4Gb	x4	1525	IDT	C0/A3	
Micron	MTA72ASS4G72LZ-2G1A1	32GB	15	E	Micron	MT40A2G4TRF-093E:A	4Gb	x4	1418	IDT	C0 / B1	
Micron	MTA72ASS4G72LZ-2G1A1	32GB	15	E	Micron	MT40A2G4TRF-093E:A	4Gb	x4	1418	Montage	B1 / A1	

Notes:

All LRDIMM parts are DDP (Dual Die package);

All parts are recommended to be run, using latest Intel® Platform reference Code Production Version.

Modules with the date codes within the Intel® Xeon® E5-2600 v3 processor family and the Intel® Xeon® E7-8800/4800 v3 processor family new date codes considered low risk.

